

**Question B1: Networking**

- 1) Explain why there exist four address fields in the IEEE 801.11 WLAN frame format. *Remark: Consider the different communication possibilities between the involved wireless network elements.*
- 2) What is the difference between a peer- and a overlay model in VPNs?
- 3) Which frame field distinguishes between group members in a VLAN?
- 4) Which two signaling protocol families exist in IP networks?
- 5) What is the difference between a leaky bucket and a token bucket?

**Question B2: Circuit-Switching**

- 1) Give three major differences between SDH and OTN.
- 2) How are PDH- and packet-technologies principally mapped onto SDH?
- 3) Which functionality does LCAS provide?
- 4) What is inverse multiplexing and what is the term in Ethernet?
- 5) Which units can be labelled by GMPLS?
- 6) What is respectively a lightpath, a lightbus, and a lighttree?

**Question B3: Packet-Switching**

- 1) Give the architecture of super-high-speed Routers.
- 2) Give the architecture and network components of GPRS.
- 3) Give the architecture and network components of IMS.
- 4) Give the architecture and properties of RPR.
- 5) Give the architecture and properties of PPP.

**Question B4: Wireless Access**

- 1) What are the characteristics of FDD and TDD in UMTS?
- 2) Which channel groups (no individual channels) do exist in GSM?
- 3) Give three characteristics of WiMax.
- 4) For which network environment MBMS has been developed?
- 5) What are respectively the duplex modes of WLAN and WiMax?
- 6) What are WPANs and WRANs?

**Question B5: Wired Access**

- 1) Give the properties of a V.90/92 modem.
- 2) Give the transmission principle and data forming principle of xDSL.
- 3) Give the transmission and access principles of APON and EPON.
- 4) Which access system uses the standard DOCSIS?
- 6) What are the properties of Powerline?

**Question A1: Components for Networking Applications**

- 1) What are the main trends in semiconductor electronics and particularly in integrated circuits?
- 2a) What technologies and semiconductor materials are used to manufacture integrated circuits for communications applications?
- 2b) What types of fibers are used in optical communications?
- 3a) How are the transmission windows of standard single-mode fiber defined?
- 3b) Which new fiber types exist and what are the trends in optical communications?
- 4a) Draw a schematic structure of an erbium-doped fiber amplifier (EDFA).
- 4b) Which other optical amplifiers can be used in fiber communications?
- 4c) Describe the operational principle of these optical amplifiers and in which applications they can be used.

**Question A2: Interconnects and Systems**

- 1a) How interconnects can be classified?
- 1b) Compare at least three typical interconnection solutions with each other regarding physical specification of signal transmission, structure, addressing method, flexibility, applications, transaction overhead or transmission efficiency.
- 2a) What is Internet SCSI (iSCSI)?
- 2b) Describe encapsulation of storage data into TCP/IP packets by using the iSCSI protocol
- 3a) There are three options for implementing iSCSI host bus adapters (HBA). Describe these implementation options.
- 3b) What option can provide the highest performance?
- 4a) Draw a block diagram of the 10GBASE-R (10 Gigabit Ethernet) physical coding sublayer (PCS).
- 4b) Describe the main functions of the blocks.
- 4c) What coding scheme is used in 10GBASE-R?
- 5a) Describe SONET/SDH interfaces developed by the Optical Internetworking Forum (IOF).
- 5b) What are the main differences between System Packet Interface (SPI) and DERDES Frame Interface (SFI)?